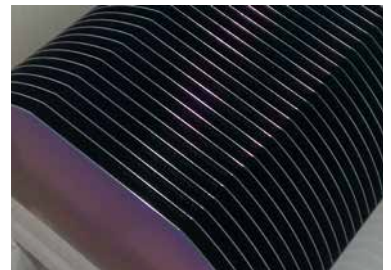
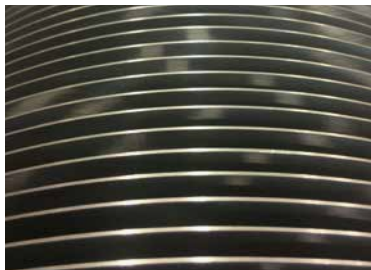
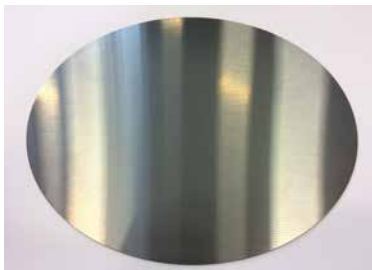


DW 292-300

MULTI WIRE SAW



WORK PIECE DIMENSIONS:
MAX. Ø 305 MM × 650 MM



12" WAFER AT HIGHEST PRECISION AND THROUGHPUT

- ✔ Slurry and Diamond Wire compatible
- ✔ High wire speed and acceleration
- ✔ Minimized deflection roller amount
- ✔ High process automation

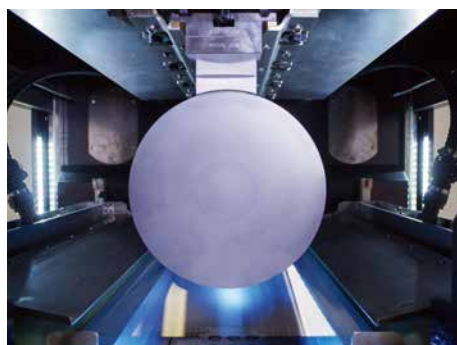
SMART SLICING TECHNOLOGY FOR SEMICONDUCTOR WAFERING

HIGHLIGHTS DW 292-300

- ✔ Slurry and Diamond Wire compatible
- ✔ Fast and easy change to Diamond Wire
- ✔ High throughput:
35 m/s wire speed,
12 m/s² acceleration
- ✔ 60 μm wire capability
- ✔ Perfect accessibility for daily operation
- ✔ Robust machine: Mineral cast, low temperature dependency, low vibration, low noise
- ✔ Shortest wire path in market: easy wire set-up and constant tension
- ✔ New HMI on 19" touch screen, production assistant, global process recipes, easy to train, easy to use
- ✔ Option: Automatic cutting fluid exchange
- ✔ Option: MES interface (SECS/GEM300)



Long load length for high output



Optimized axis distance for higher wafer quality



Easy operation for higher yield

TECHNICAL DATA	DW 292-300 FEATURES
Web length [mm]	660
Max. work piece dimensions [mm]	Ø 305 × 650
Wire speed [m/sec]	Slurry: 20 / DW: 35
Wire acceleration [m/s ²]	Slurry: 8 (< 3 s) / DW: 12 (< 3.5 s)
Min. wire diameter [μm]	60
Max. wire tension [N]	45
Deflection Roller [pcs]	6
Wire guide roller [pcs]	3
Cutting fluid tank [l]	300
Machine dimensions [L × W × H] [mm]	3800 × 1380 × 2860
Machine weight [kg]	10600

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TOGETHER WE WILL FIND A SOLUTION
FOR YOUR REQUIREMENTS

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